

Title (en)

Method for inspecting and judging photomask blank or intermediate thereof

Title (de)

Verfahren zur Prüfung und Beurteilung eines Photomaskenrohlings oder eines Zwischenprodukts davon

Title (fr)

Procédé d'inspection et d'évaluation d'une ébauche de masque photolithographique ou intermédiaire de celui-ci

Publication

EP 2237109 A3 20110817 (EN)

Application

EP 10250686 A 20100331

Priority

JP 2009086173 A 20090331

Abstract (en)

[origin: EP2237109A2] A photomask blank having a film on a substrate is inspected by (A) measuring a surface topography of a photomask blank having a film to be inspected for stress, (B) removing the film from the photomask blank to provide a treated substrate, (C) measuring a surface topography of the treated substrate, and (D) comparing the surface topography of the photomask blank with the surface topography of the treated substrate, thereby evaluating a stress in the film.

IPC 8 full level

G03F 1/32 (2012.01); **G03F 1/60** (2012.01); **G03F 1/68** (2012.01); **G03F 7/20** (2006.01)

CPC (source: EP KR US)

G03F 1/84 (2013.01 - EP KR US); **G03F 7/70783** (2013.01 - EP KR US); **G03F 7/70916** (2013.01 - KR); **H01L 21/0274** (2013.01 - KR); **H01L 21/0337** (2013.01 - KR); **H01L 22/30** (2013.01 - KR)

Citation (search report)

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- [X] EP 0403220 A1 19901219 - SONY CORP [JP]
- [X] WO 2008151083 A1 20081211 - KLA TENCOR CORP [US], et al
- [Y] US 2005019678 A1 20050127 - NAKATSU MASAYUKI [JP], et al
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Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO SE SI SK SM TR

Designated extension state (EPC)

AL BA ME RS

DOCDB simple family (publication)

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DOCDB simple family (application)

EP 10250686 A 20100331; CN 201010158156 A 20100331; JP 2009086173 A 20090331; KR 20100026602 A 20100325; TW 99109637 A 20100330; US 75002310 A 20100330